



**European Semiconductor  
Packaging, Assembly and Test**

Supported by:



**Dear ESPAT member.**

Thank you for attending the “face to face” inaugural meeting of the ESPAT consortium on Wednesday 8 October, or if you were unable to make it there, thank you for your continued interest in ESPAT.

Please see below a brief transcription (minutes) of the meeting which summarises the discussions and proposed actions. It is hoped that the ongoing enthusiasm will carry forward these actions and that you will continue to give your support.

As requested, copies of the presentations, the SEMI ESPAT proposed SIG brief, a copy of the attendee register and a “member” contact list are attached.

Sincerely,

ESPAT Management Panel:

Andy Longford - Panda Europe & SEMI APC Co-Chair

Steffen Kroehnert - Nanium & SEMI APC Co-Chair

Yann Gillou - SEMI Europe

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**Meeting REPORT .**

Date: Wednesday, 8 October 2014, at Semicon Europa Grenoble, France.

Time: 3.30 – 5.00 pm

Location: Room “Bayard”

The meeting was attended by 30 persons, as detailed in the attendee register list (**document 1**).

**Opening Welcome and Introductions**

Andy Longford (AL), of Panda Europe opened the meeting as “acting” chairperson and introduced the Agenda. Formal introductions were made by all attendees giving name, affiliation and a brief statement of their activity in the ESPAT field.

**Initial Outline and Aims of ESPAT**

AL presented a review document that outlined the reasons for proposing the ESPAT community and a detail of the initial possible aims, stating that it could be a document for discussion. A copy (**document 2**) is attached. The issue of funding and costs was raised and some examples were offered to the meeting.

**Draft Outline of SEMI SIG (Special Interest Group)**

Yann Gillou (YG) of SEMI introduced the SEMI organization approach to a Special Interest Group (SIG). He explained the purpose and “rules” of the SEMI SIG process and presented a format which could be applied to ESPAT, should the “community” wish to avail themselves of this approach. It was agreed that a copy of the SIG “draft” document should be circulated for people to review and offer comment on. This is attached (**document 3**).

It was noted by Mr Tom Salmon of SEMI USA that the SEMI packaging committee in the USA were keen to consider becoming a SIG also.

### **Declaration of Interest from Attendees**

Steffen Kroehnert (SK) of Nanium had previously circulated some questions in order to ascertain what the community would like to gain from ESPAT. SK presented the feedback from 18 responses that had been received prior to the meeting, and offered these as topics for discussion. A copy of the presentation is attached (**document 4**).

### **Review/ Discussions of ESPAT Aims**

The meeting was opened up for questions, comments and discussion about the possible adoption of the SIG format, the aims proposed for ESPAT and what its objectives should be. Some comments are recorded as follows:

- It was noted that the Advanced Packaging Conference (APC) which had just concluded, had 2 keynotes, one from Continental (Automotive) and one from Airbus, that both put out an appeal for better support from the European packaging community.
- A number of community members are already working together on “funded” projects involving ‘back-end’ technologies
- TEST was a key function for Europe and it was felt that more emphasis should be put on this topic in ESPAT.
- A number of comments suggested that there was a need to keep more “back-end” revenue in Europe.
- ASE commented that they would happily consider investing in manufacturing in Europe should the right opportunity present itself.
- ESPAT should consider what are the key “applications” that should be supported in Europe
- The community should be able to show comprehensively what its strengths are.
- Training for applications of the emerging package technologies should be a key consideration

### **Proposals for Actions and next Steps**

A summary of the proposals suggested is:

- The meeting proposed that all attendees should be considered “de-facto” members of ESPAT at this time, until a formal organizational and operational case was in place.
- 70% of the attendees were in favour of adopting the SEMI SIG format
- A poll of attendees noted that only 18 of the 30 were already SEMI member companies.

The meeting proposed that the first activity (Task 1) should be to document capabilities in P,A and T of each of the ESPAT community members and document what the needs (wants) of these members are in terms of Package assembly and test capability. This would then enable the community to have a better understanding of the strengths and weaknesses, but more importantly enable the community to work with one another to take advantage of the capabilities.

AL agreed to take on the task and formulate a document to enable the survey.

A list of member contact e-mails was requested and a copy is attached (**document 5**)

### **Final review and wrap-up**

AL briefly reviewed the actions and summarized the outcome. It was clear that a number of questions need to be raised such that:

- The meeting had enabled the formation of a community (ESPAT) that agrees in principle to communicate with one another
- The high level of interest already expressed in the development of the community indicated that ESPAT could be a successful entity
- The community would like a clearer picture of what ESPAT represents in terms of being beneficial to a business

AL agreed to provide a meeting report and circulate the requested documents.

### **NEXT MEETING**

SK noted that the next ESPAT-Consortium-Meeting is planned for Friday 24 April 2015, following the SEMI Networking Day Q2/2015 (23 April) with the theme: "European ShowCase – Semiconductor Packaging, Assembly and Test", hosted by NANIUM S.A. in Vila do Conde, Portugal.

The meeting closed at 1700 hrs.